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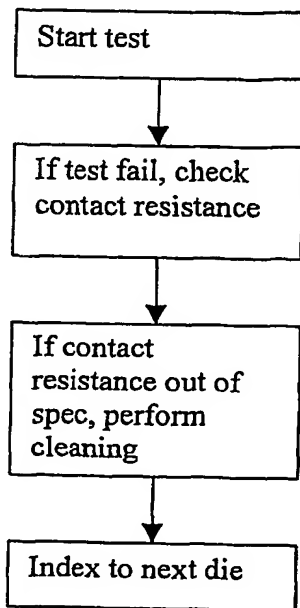
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(54) Title: **PROBE CARD NEEDLE CLEANING FREQUENCY OPTIMIZATION**



(57) Abstract: A system and method for optimizing cleaning of a probe card including using the probe card to test the functionality of dies on a wafer, when a die fails the probe test, and the probe reports failure to contact the pads of the die, checking the resistance of the probe needles, and if the resistance of a probe needle is greater than a predetermined value triggering probe needle cleaning.

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